

L200TWYG4B

Yellow/Hi-Eff Green

5mm, Flanged Domed, 8.6mm Height
45° viewing angle

DWG BY:
BL / GP
10-17-06

QA:
RD
03-25-14

R&D:
BJ
03-25-14

REVISION LTR: A
ECR#: 032414-RTD01
03-25-14

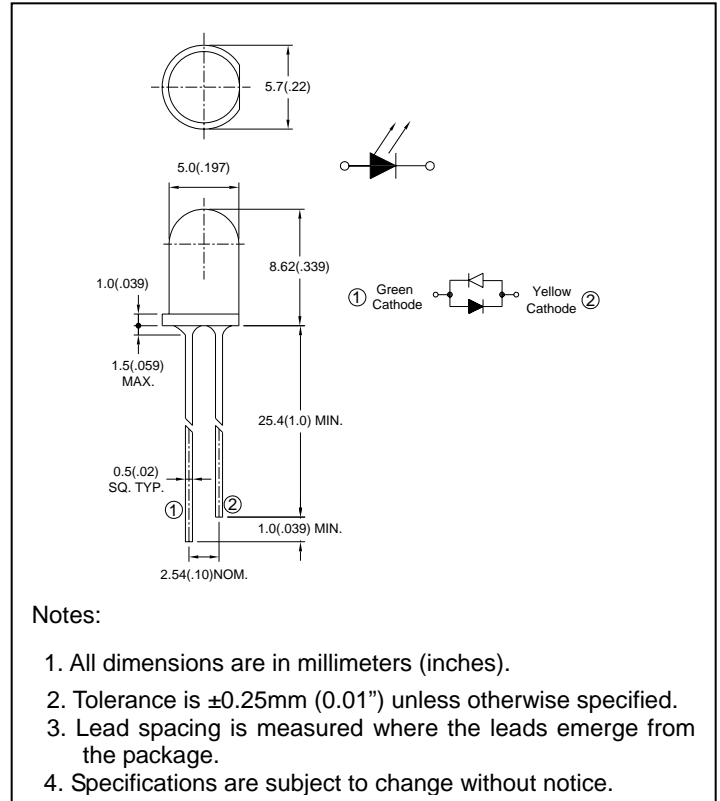
● **Features:**

1. Chip material: GaAsP/GaP(Yellow)
and GaP/GaP(Green)
2. Emitted color : Yellow and Green
3. Lens Appearance : White Diffused
4. Low power consumption.
5. High efficiency.
6. Versatile mounting on P.C. Board or panel.
7. Low current requirement.
8. 5mm diameter package.
9. This product is RoHS compliant.

● **Applications:**

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● **Package dimensions:**



● **Absolute Maximum Ratings(Ta=25°C)**

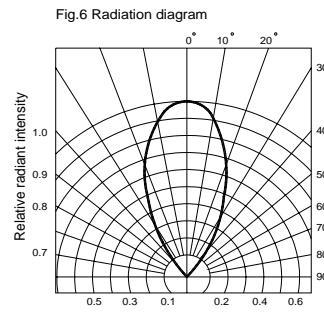
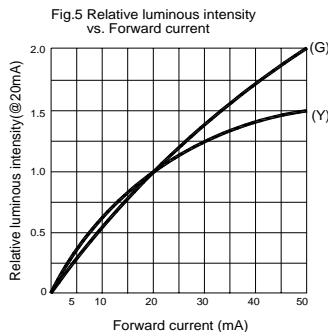
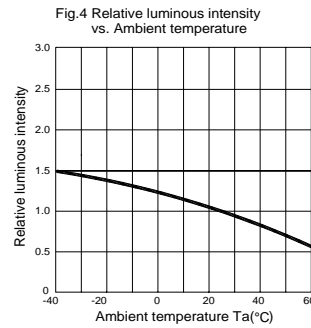
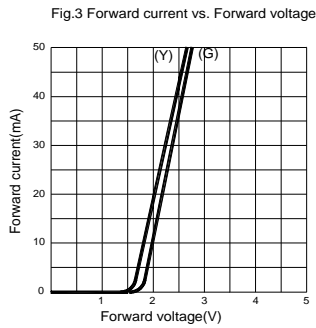
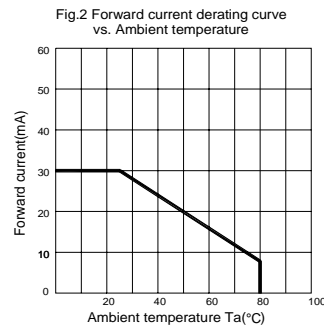
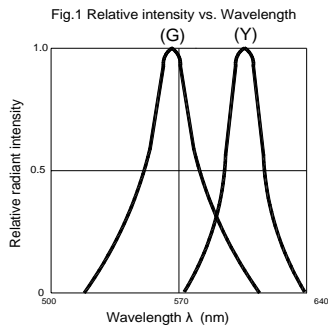
Parameter	Symbol	Yellow	Green	Unit
Power Dissipation	Pd	80	80	mW
Forward Current	I _F	30	30	mA
Peak Forward Current* ¹	I _{FP}	150	150	mA
Operating Temperature	Topr	-40°C ~ 85°C		
Storage Temperature	Tstg	-40°C ~ 100°C		
Soldering Temperature	Tsol	260°C max (for 5 seconds)		
Hand Soldering Temperature	Tsol	350°C max (for 3 seconds)		

*¹Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

● **Electrical and optical characteristics(Ta=25°C)**

Parameter	Symbol	Condition	Color	Min.	Typ.	Max.	Unit
Forward Voltage	V _F	I _F =20mA	Yellow Green	-	2.1 2.2	2.6 2.6	V
Luminous Intensity	I _v	I _F =20mA	Yellow Green	-	10 18	-	mcd
Reverse Current	I _R	V _R =5V	Yellow Green	-	-	100	μA
Peak Wave Length	λ _p	I _F =20mA	Yellow Green	-	585 565	-	nm
Dominant Wave Length	λ _d	I _F =20mA	Yellow Green	- -	588 571	- -	nm
Spectral Line Half-width	Δλ	I _F =20mA	Yellow Green	- -	36 30	-	nm
Viewing Angle	2θ _{1/2}	I _F =20mA	Yellow Green	-	45	-	deg
Chromaticity Coordinates	X	I _F =20mA	Yellow	-	0.56	-	
	Y				0.44		
Chromaticity Coordinates	X	I _F =20mA	Green	-	0.45	-	
	Y				0.54		

● **Typical Electro-Optical Characteristics Curves**



● **Lead Frame Dipping**

The LED Lead Frame are dipped by Sn in order to protect the rust. Also the dipping thickness is Max 5 μm . When soldering, leave 2.0mm of minimum clearance between the resin and the soldering point.

● **DIP soldering (Wave Soldering)**

Preheating : 120°C ,within 120~180 sec.
 Operation heating : 255°C \pm 5°C within 5 sec. 260°C (Max)
 Gradual Cooling (Avoid quenching).

